

New Development Alconano® Ag Paste

ALCONANO

For power modules
Si and SiC die attach

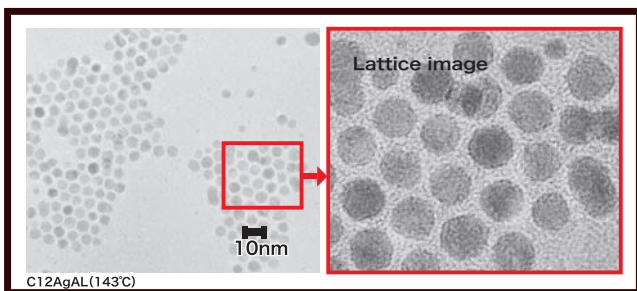
New Product

Die Bonding Nano Material Alconano® Ag paste

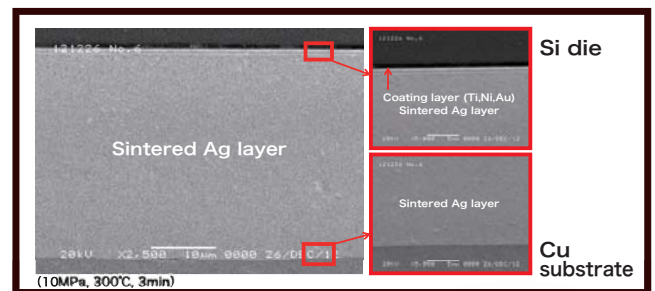
Features

- Low temperature assembly by non-pressure sintering from 200°C available.
- Superior in thermal cycling performance, thermal conductivity, and electrical conductivity.

TEM images



SEM of cross-section of the sintered joint



Application Examples

- Power Modules
Bonds to Si, SiC, Cu, and Au
- LED Chips
- Solar Panels



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